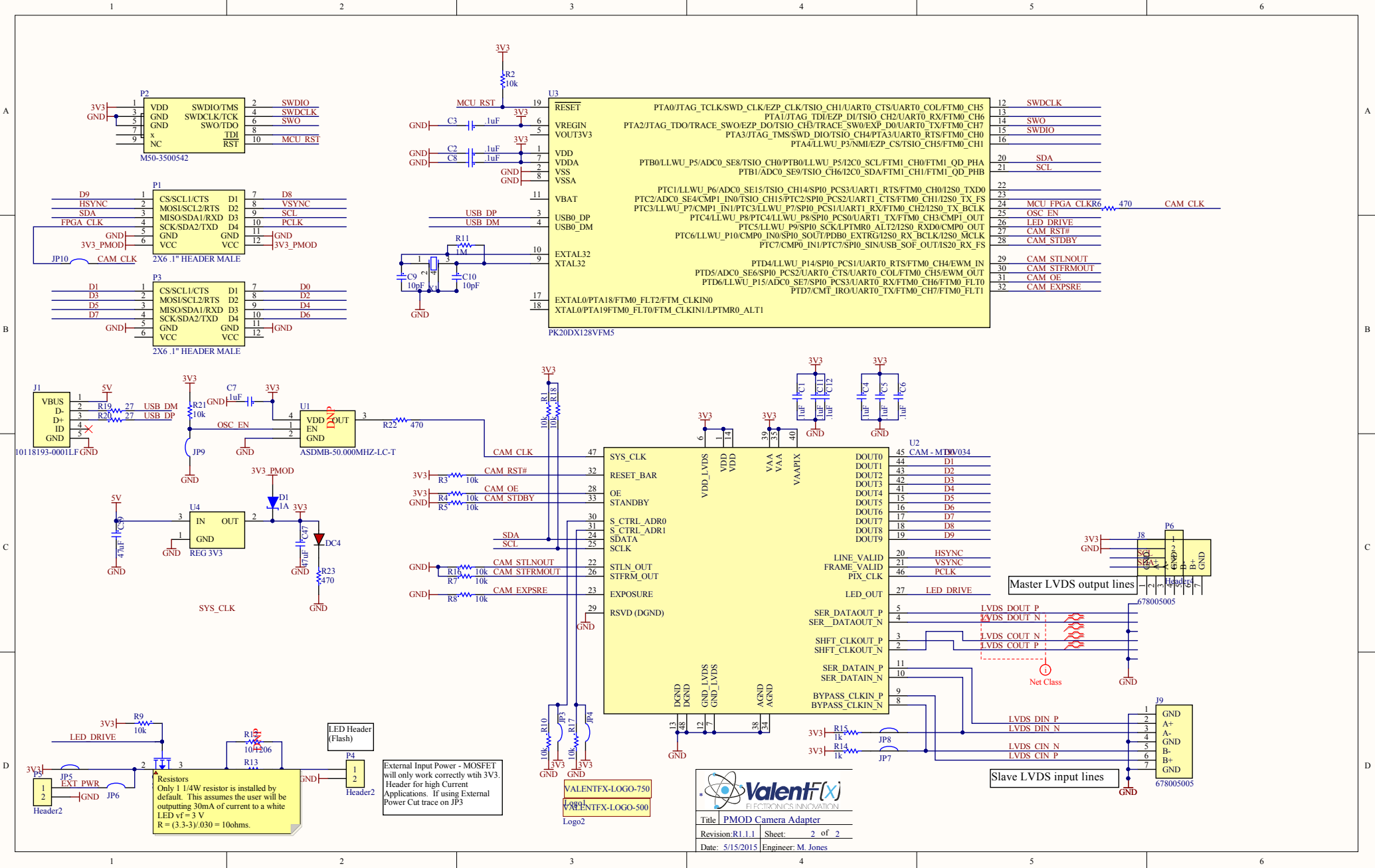


U_logi-cam-mt9v
logi-cam-mt9v.SchDoc



PCB Fabrication Notes

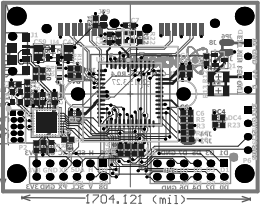
Unless otherwise specified, all dimensions are in inches
Overall Dimension: 1.7" x 1.4"
Finished Thickness: .062"
Layer Count: 2
Min Thru Hole: 13 mil
Annular Ring: 7 mil
Min Trace/Space: 6 mil
Drill Count: 179
PAD Count: 266
Component Count: 64
Via Count: 125

Plating: Gold ENIG
Solder Mask: Black
Legend: White Non-Conductive Ink LPI Process
RS274-X Gerber Format, 2.5 Leading Zeros Suppressed
Excellon Drill Format, 2.5 Trailing Zeros Suppressed

Layer Details	4-Layer Stackup	POLARITY
.GTL - Top Copper		POSITIVE
.G1 - Inner Copper (Ground)		POSITIVE
.G2 - Inner Copper (VDD)		POSITIVE
.GBL - Bottom Copper		POSITIVE

.GTO - Top Silkscreen
.GBO - Bottom Silkscreen
.GTP - Top Solder Paste
.GBP - Bottom Solder Paste
.GTS - Top Solder Mask
.GBS - Bottom Solder Mask
.GKO - Board Outline
.GM1 - 3D Part Bodies - System
.GM2 - Board Dimensions
.GM3 - Single Board Fabrication Notes
.GM4 - Single Board Score/Tab Route
.GM13 - 3D Body Alt
.GM15 - Assembly Outlines - Top
.GM20 - Panel Dimensions
.GM21 - Panel Score/Tab Route
.GM22 - Panel Dimensions

.TXT/.DRL - NC-Drill



Group VIII Technology 1652 W 820 N Provo, UT 84601 801/379-0118	PCB DESIGNER: Michael Jones		TITLE:	
	DATE: 5/15/2015		PART NO.:	REV:
	FILE NAME: Bsp-cam-mthn_PcbDoc		DWG NO:	SCALE: